





FORM HC0011-5-8

(5) Excessive force may cause the connector to fail or become damaged. Please handle the connector with care and make sure that it does not deform in any way. In particular, avoid the following if you will be performing card recognition and operating inspections in your assembly process without installing the product to an enclosure. · Do not insert or withdraw cards at an angle, whether in a vertical or lateral direction. · Do not insert or withdraw a partially inserted card by prying it in a vertical or lateral direction. HRS DRAWING FOR Condition. (6) Recommended conditions of reflow <Impossible area to surface mounting adhesive> 250 Reflow atmosphere : Ambient air N₂ Temperature(°C) (50秒) Solder : Cream type Sn/3. OAg/O. 5Cu (M705-GRN360-K2-V made by Senju Kinzoku) Soldering Board tested : 60×100×1mm glass epoxy Metal mask thickness : 0.15mm 90~120秒 Number of reflow cycles : ※Two cycles max 100 Preheating Surface mounting adhesive This temperature profile applies to the conditions stated above. Impossible area (shaded area) 50 中中 Since temperature profiles can vary depending on the type and manufacturer of the cream solder used, as well as board size Surface of the product and other factors including conditions of the parts to be mounted. Time (Seconds) make sure to check the mounting conditions carefully before use. ≫Please use surface mounting adhesive when reflow back side.

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HS.

(7) Please do not use a prying motion to withdraw an engaged SD card. This can cause damage to the SD card and/or connector. (8) Please clean the SD card if there is insert or withdraw feel is bad or contact defect for a specific SD card. (9) Markings for preventing incorrect card insertion If you will be displaying markings or instructions to prevent end users from inserting the card incorrectly, please pay extra attention to the text description and the direction of the marking used to indicate the correct direction. (10) This product is equipped with an ejection function. Never wash the entire connector as this could lead to problems with this function. If it must be washed, wash only the soldered areas and make sure that you do no leave any cleaner residues on the connector. Cleaner residues can cause problems with card insertion/extraction and electrical performance. (11) This is a connector designed to be mounted on boards. (13) You may find some processing liquid residue on the surface of the product but this has no effect on its quality.

(14) Due to the material used, the surface of a SD card will be subject to sliding acceptable.

(15) It is timestate. (14) Due to the material used, the surface of a SD card will be subject to sliding scratches but this will not affect product quality or performance.) It is tin-plating to part of the metal cover.

There is a change in gloss and appearance before and after reflow for the appearance of the tin-plated part, but this will not affect product quality or performance. (15) It is tin-plating to part of the metal cover.

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	PART NO.	DM1AA-SF-PEJ(82)	
	CODE NO.	CL0609-0004-8-82 /2	5

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